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# **A Comparative Analysis of Studies on Heat Transfer and Fluid Flow in Microchannels<sup>1</sup>**

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## **ABSTRACT**

The extremely high rates of heat transfer obtained by employing microchannels makes them an attractive alternative to conventional methods of heat dissipation, especially in applications related to the cooling of microelectronics. A compilation and analysis of the results from investigations on fluid flow and heat transfer in micro- and mini-channels and microtubes in the literature is presented in this review, with a special emphasis on quantitative experimental results and theoretical predictions. Anomalies and deviations from the behavior expected for conventional channels, both in terms of the frictional and heat transfer characteristics, are discussed.

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Amongst the novel methods for thermal management of the high heat fluxes found in microelectronic devices, microchannels are the most effective at heat removal. The possibility of integrating microchannels directly into the heat-generating substrates makes them particularly attractive, since thermal contact resistances may be avoided. The two important objectives in electronics cooling – minimization of the maximum substrate temperature and reduction of substrate temperature gradients – can be achieved by the use of microchannels.

A large number of recent investigations have undertaken to study the fundamentals of microchannel flow, as well as to compare the flow and heat transfer characteristics of microchannels with conventional channels. A comprehensive review of these investigations conducted over the past decade is presented here in concise tabular form.

Predictive correlations have also been proposed in the literature, based on experimental investigations on liquid and gas flow in microchannels. Various combinations of channel size, pitch and substrate material have been considered. Generally, these correlations have been cast in the same forms as conventional relationships for larger-diameter tubes and channels, but have included modified coefficients. A comparative study of the correlations for single-phase flow is presented in this review.

## **REVIEW OF THE LITERATURE**

Studies on microchannel flows in the past decade are categorized into various topics and summarized in Table 1. The literature survey extends over a wide range of topics such as measurement and estimation of friction factor and heat transfer in microchannels and small-diameter tubes, comparison with flow in conventional channels, investigation of single-phase, boiling and two-phase flows in microchannels, mini channels and small tubes, gas flow in microchannels, analytical studies on microchannel flows, and design and testing of microchannel

heat sinks for electronics cooling. For each study, key descriptors of the cooling configuration and the primary observations are included.

## **QUANTITATIVE COMPARISONS**

A comparative study of correlations for single-phase flow and heat transfer in microchannels proposed by various investigators is presented in this section. Correlations for friction factor and heat transfer, in the laminar and turbulent regimes are compared, and contrasted with conventional correlations for macrotubes and channels. Details of each of the studies discussed in this section are available in Table 1.

### **Friction Correlations**

Correlations for friction factor have been proposed based on experiments with nitrogen and water as working fluids [3, 9, 36] in trapezoidal and rectangular channels and microtubes. Peng et al. [13] analyzed water flow in rectangular channels to obtain correlations for various combinations of the channel hydraulic diameter and channel pitch in rectangular channels for laminar and turbulent flow. A plot of the friction factor correlations proposed for laminar and turbulent flow in microchannels is shown in Fig. 1. The graph shows the product of friction factor and Reynolds number ( $f \cdot Re$ ) plotted against the Reynolds number. Conventional correlations are also included for comparison: the Blasius correlation ( $f = 0.140 Re^{-0.182}$ ) is used for turbulent flow, while for laminar flow, circular-pipe ( $f = 64/Re$ ) and square-channel predictions ( $f = 57/Re$ ) are shown. The  $f \cdot Re$  product is independent of Reynolds number for laminar flow in conventional channels. In the turbulent regime, the friction factor is almost independent of the Reynolds number ( $f \cdot Re$  increases linearly with  $Re$ ). The predictions in the

literature for microchannels may be analyzed with greater ease by considering the laminar and turbulent regions separately.

Predictions of  $f \cdot Re$  in the laminar regime are shown in Fig. 2. The correlations of Wu and Little [3], Choi et al. [9] and Yu et al. [36] predict constant values of  $f \cdot Re$ , with the magnitude of this product being greater than for conventional channels in Wu and Little (110), and lower in Choi et al. and Yu et al. (55 and 50 respectively). Predictions from Peng et al. [13] for water flow in rectangular microchannels (see Table 2 for details) show an altogether different trend: in all cases,  $f \cdot Re$  decreases with an increase in the Reynolds number. For cases A, B, and C from Peng et al. (in which  $D_h \geq 267 \mu m$ ), the laminar regime extends to  $Re \approx 700$ , whereas for cases E, F, and G ( $D_h \leq 200 \mu m$ ), the onset of turbulence occurs as early as  $Re = 300$ . (As in the original work, the laminar plots for cases A through D are extended till  $Re = 1000$ ). While the slopes of the curves for all test cases are identical ( $Re^{-0.98}$ ), the magnitude of  $f \cdot Re$  is highest for the largest microchannels ( $D_h$ ) and lowest for the smallest.

The friction correlations in the turbulent regime are compared with conventional correlations in Fig. 3. Predictions for nitrogen flow from Choi et al. agree very well with conventional results; the Wu and Little correlation is similar to these two in its trend of variation, but the predicted values are much higher in magnitude. The correlations of Peng et al. [13] for water flow again exhibit a very different trend: in all cases,  $f \cdot Re$  decreases with an increase in Reynolds number (as  $Re^{-0.72}$ ), in contradiction to conventional correlations. The onset of turbulence is also seen to occur much earlier for the microchannels studied by Peng et al. Another observation of interest in Fig. 3 is that the  $f \cdot Re$  values predicted by Peng et al. decrease in magnitude as the channel hydraulic diameter decreases; the drop in  $f \cdot Re$  with  $D_h$  is very steep when  $D_h$  becomes smaller than  $200 \mu m$ .

## Heat Transfer Correlations

Correlations for the average Nusselt number in microchannels in terms of the Reynolds and Prandtl numbers have been proposed in the literature for laminar and turbulent regimes, based on experiments with a range of fluid-substrate combinations, channel dimensions and configurations, as summarized in Table 1.

Heat transfer correlations for nitrogen flow [4, 9, 36], water flow in rectangular microchannels [12, 14, 16], water flow in circular microchannels [20, 36], and methanol in rectangular channels [12] are considered for comparison. Figure 4 shows a composite plot of predicted values of  $Nu/Pr^{0.33}$  as a function of Reynolds number from the correlations in these studies. Conventional-channel correlations are also included for comparison: the Dittus-Boelter correlation for turbulent flow in conventional channels, and for laminar flow,  $Nu_{Dh} = 1.86 (Re_{Dh} Pr)^{0.33} (D_h/L)^{0.33}$ ; a sample set of parameters ( $L = 50$  mm and  $D_h = 0.24$  mm) is used to compute values from this correlation. A significant amount of scatter is seen in these plots, as was true for predictions of friction factor, with the predictions of Choi et al. [9] and Yu et al. [36] being among the highest in the turbulent regime. All predictions reflect an increase in Nusselt number with increasing  $Re$ .

The heat transfer correlations are again considered separately in the laminar and turbulent regimes in Figs. 5 and 6 respectively. The end of the laminar regime was identified to be at quite different Reynolds numbers in the studies considered, as noted with the friction factor predictions. The dependence of Nusselt number on Reynolds number is stronger in all the microchannel predictions when compared to conventional results, as indicated by the steeper slopes of the former; Choi et al. [9] predict the strongest variation of Nusselt number with  $Re$ . Also, the predictions for all cases from Peng et al. fall below those for a conventional channel.

In the turbulent regime (Fig. 6), the predictions of all investigators with the exception of Peng et al. [14] and Peng and Peterson [16] fall above the conventional channel values. In particular, Adams et al. [20] and Wu and Little [4] lie in one group. The predictions of Choi et al. [9] and Yu et al. [36] are also somewhat comparable, and lie in a different group. It may be noted that these groups are not divided by fluid type (since both groups include results for nitrogen and water) or by microchannel dimensions. The rectangular microchannels of different dimensions (Table 2) considered in Peng et al. [14] exhibit a large variation in predicted Nusselt numbers. In all these results, as well as for Peng and Peterson [16], the predicted values lie below those from the Dittus-Boelter correlation. Turbulent heat transfer predictions for case D are not included in this comparison since it appears that the value of  $C_{h,t}$  for this case may have been erroneously listed in [14] as 0.0926, and instead, should have been 0.00926. This latter value would more closely match other values for  $C_{h,t}$ , and would also result in the predictions for case D lying in the same group as cases A, B and C.

## CONCLUSION

A comparative study of the results of investigations in the literature on flow and heat transfer in microchannels has been compiled in tabular form, under various research topics. Correlations for single-phase friction factor and Nusselt number proposed by various investigators based on their experiments have been compared and contrasted with conventional correlations for larger, conventional tubes and channels in the laminar and turbulent flow regimes. A number of working fluid and substrate combinations, and shapes and configurations of the microchannels are included in this comparison. Little agreement is seen between the predictions of different investigators. The results are also not seen to be distinguished by fluid or substrate type or by microchannel dimensions and shapes.

The comparative study presented here points to differences between the flow and heat transfer in microchannels and that in channels of conventional sizes. However, the information in the literature thus far does not point to unequivocal trends of variation or reasons for such trends. There is no evidence that continuum assumptions are violated for the microchannels tested, most of which have hydraulic diameters of 50  $\mu\text{m}$  or more. As such, analyses based on Navier-Stokes and energy equations would be expected to adequately model the phenomena observed, as long as the experimental conditions and measurements are correctly identified and simulated. The discrepancies in predictions may very well be due to entrance and exit effects, differences in surface roughness in the different microchannels investigated, nonuniformity of channel dimensions, nature of the thermal and flow boundary conditions, and uncertainties and errors in instrumentation, measurement and measurement locations. Given the diversity in the results in the literature, a reliable prediction of the heat transfer rates and pressure drops in microchannels is not currently possible for design applications such as microchannel heat sinks. There is a clear need for additional systematic studies which carefully consider each parameter influencing transport in microchannels.

### **Acknowledgement**

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## **LIST OF FIGURE CAPTIONS**

Fig. 1. Friction-factor predictions from the literature for microchannels and conventional channels, in the laminar and turbulent regimes.

Fig. 2. Friction-factor predictions in the laminar regime.

Fig. 3. Friction-factor predictions in the turbulent regime.

Fig. 4. Heat transfer predictions from the literature for microchannels and conventional channels, in the laminar and turbulent regimes.

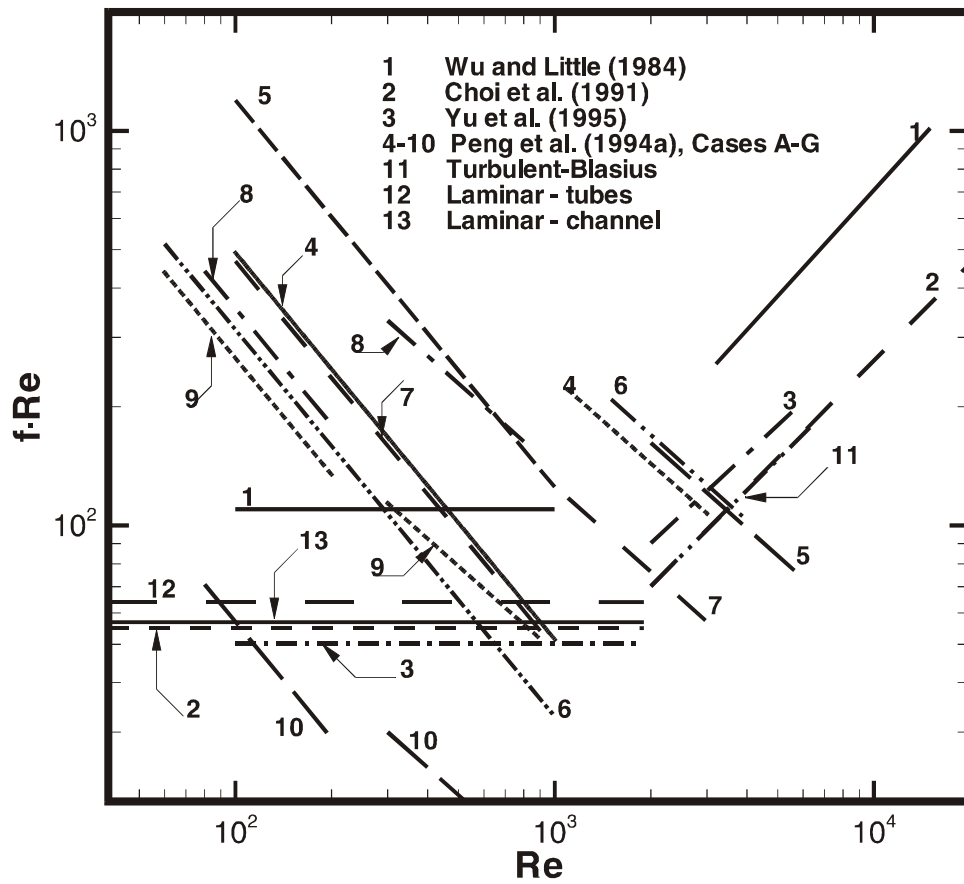
Fig. 5. Heat transfer predictions in the laminar regime.

Fig. 6. Heat transfer predictions in the turbulent regime.

## **LIST OF TABLE CAPTIONS**

Table 1. Summary of Microchannel Studies in the Literature.

Table 2. Microchannel configurations and coefficients from Peng et al. [13, 14].



**Fig. 1. Friction-factor predictions from the literature for microchannels and conventional channels, in the laminar and turbulent regimes.**

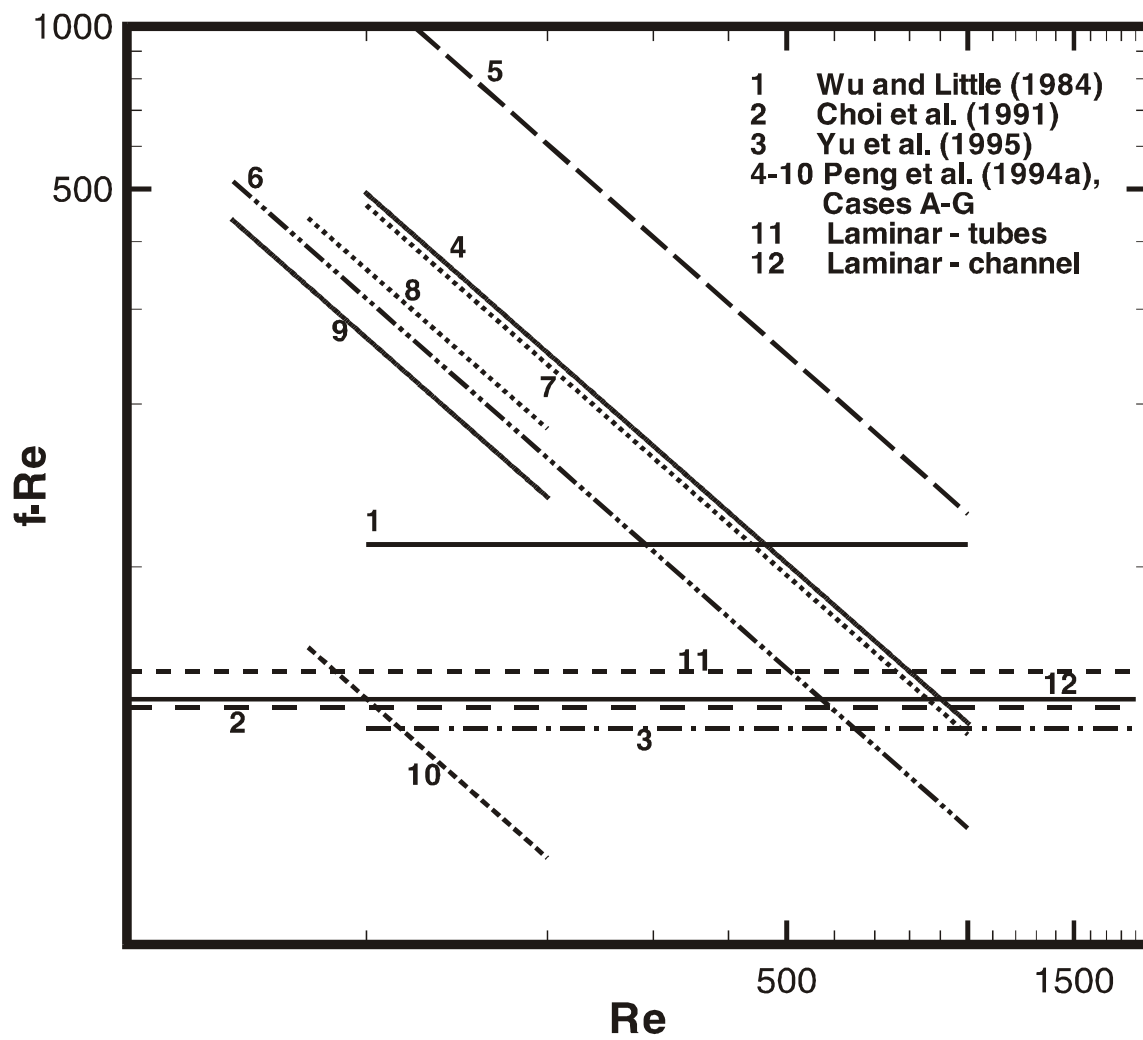
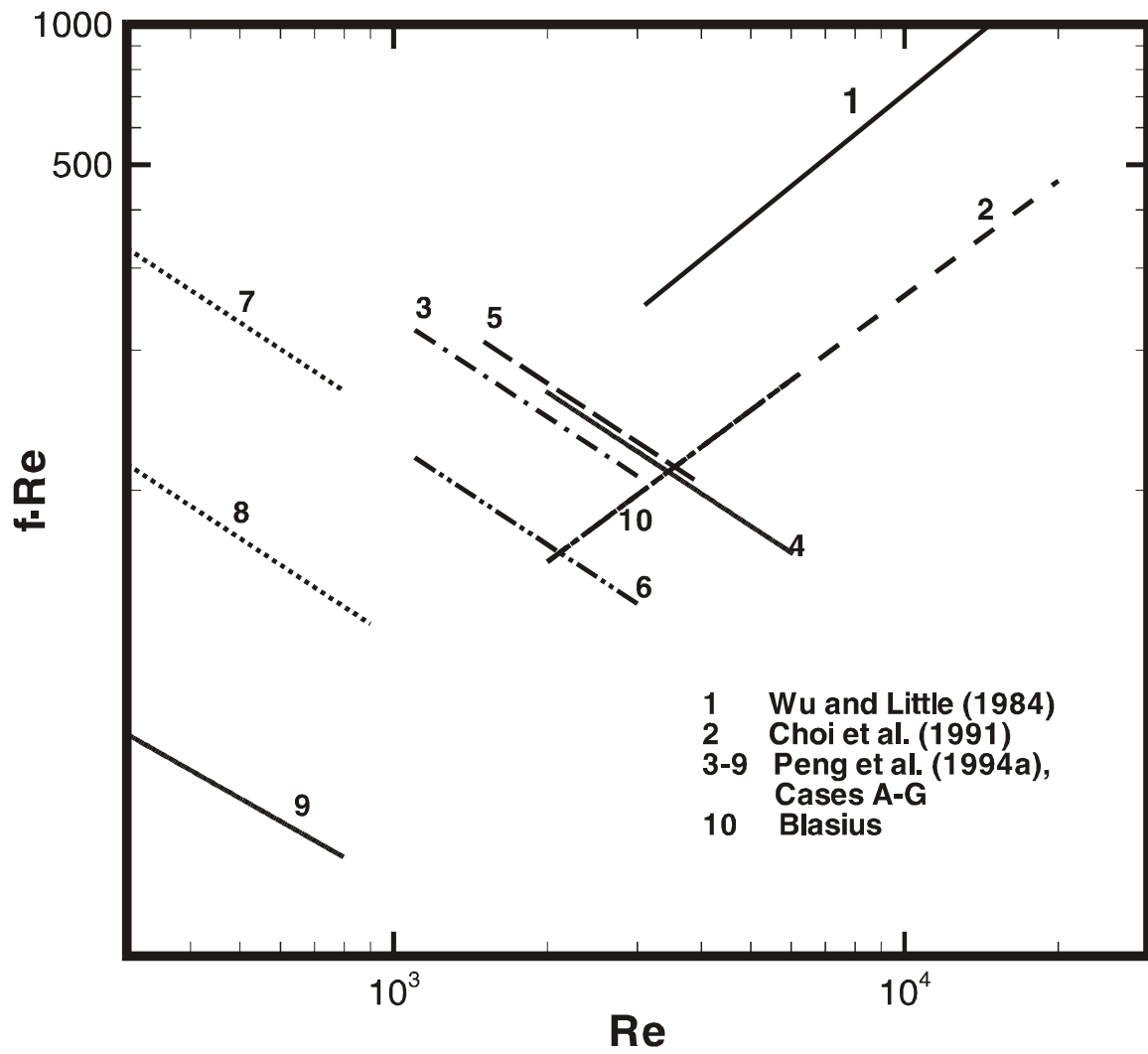
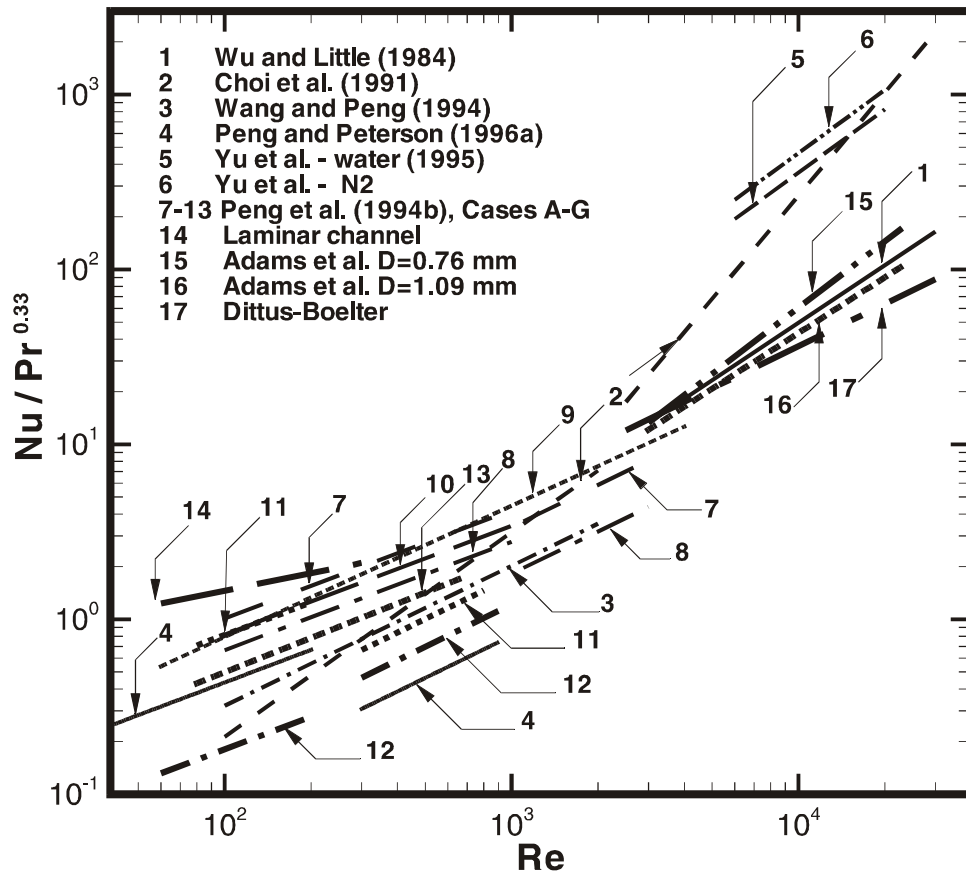


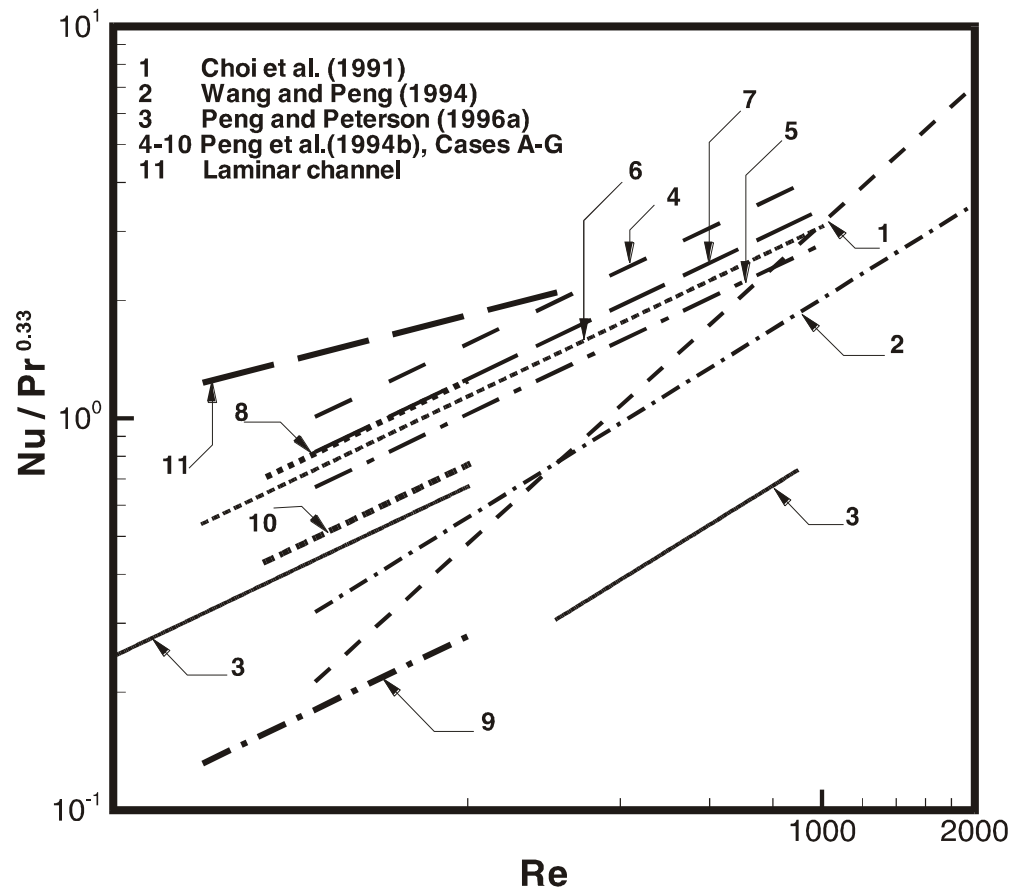
Fig. 2. Friction-factor predictions in the laminar regime.



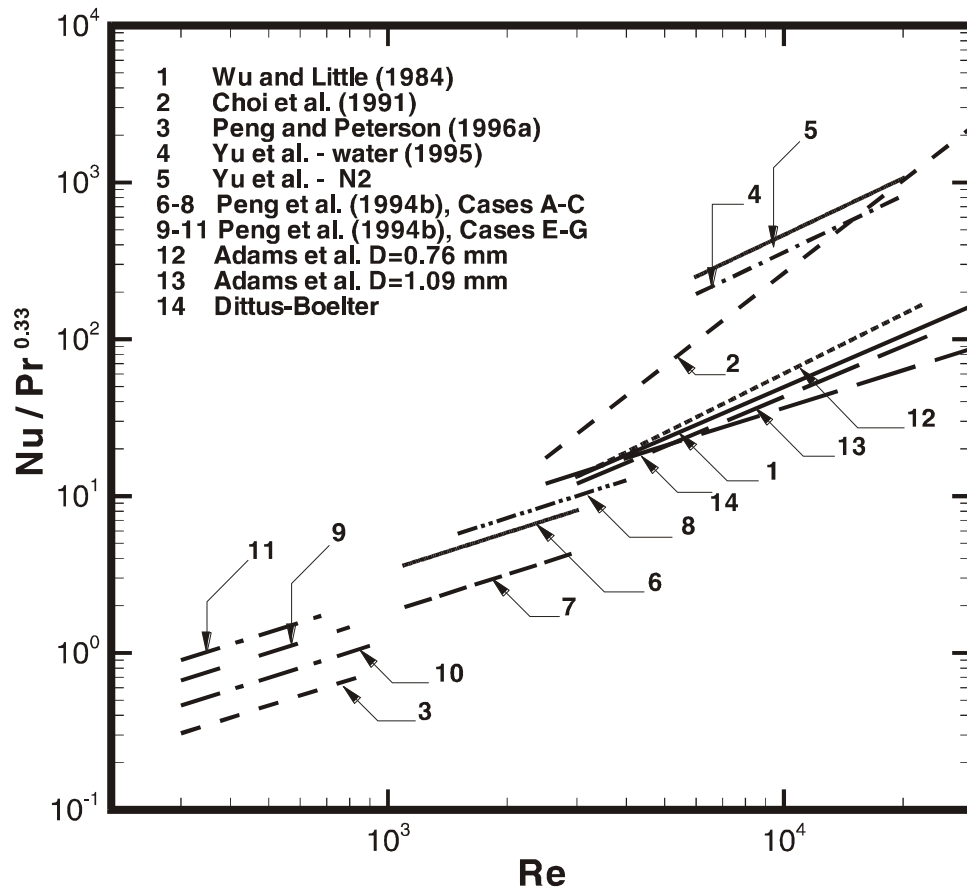
**Fig. 3. Friction-factor predictions in the turbulent regime.**



**Fig. 4. Heat transfer predictions from the literature for microchannels and conventional channels, in the laminar and turbulent regimes.**



**Fig. 5. Heat transfer predictions in the laminar regime.**



**Fig. 6. Heat transfer predictions in the turbulent regime.**

Configuration/Parameters	Nature of Work	Observations/Conclusions	Reference
<b>MICROCHANNEL CONCEPTS AND EARLY WORK</b>			
Rectangular cross section; water in silicon W = 50 $\mu\text{m}$ ; H = 300 $\mu\text{m}$ Q = 4.7, 6.5, 8.6 $\text{cm}^3/\text{s}$	Experiments on integral heat sink for silicon integrated circuits	<ul style="list-style-type: none"> <li>Demonstrated use of microchannels for very high convective heat transfer in cooling integrated circuits (790 <math>\text{W}/\text{cm}^2</math> at a substrate-to-coolant temperature difference of 71°C)</li> </ul>	Tuckerman & Pease (1981) [1]
Microchannels in cooling of integrated circuits	Microchannel fabrication and implementation details discussed	<ul style="list-style-type: none"> <li>Coolant selection, packaging/headering, microstructure selection, fabrication and bonding discussed</li> <li>Etching and precision-sawing compared; fabrication and advantages of 'micropillars' using precision-sawing discussed</li> <li>Expressions for Coolant Figure of Merit provided: CFOM = <math>(k_c \rho C / \mu)^{0.25}</math> for given coolant pressure, and <math>(k_c \rho^2 C^2 / \mu)^{0.25}</math> for given pumping power</li> </ul>	Tuckerman & Pease (1982) [2]
Trapezoidal; nitrogen in silicon and glass W = 130-300 $\mu\text{m}$ , H = 30-60 $\mu\text{m}$ , $D_h$ = 55-76 $\mu\text{m}$	Friction factors measured and compared with Moody's chart values for commercial channels	<ul style="list-style-type: none"> <li>Friction factor for glass channels 3-5 times larger than smooth-pipe predictions</li> <li>Flow transition occurred at <math>\text{Re} \approx 400</math></li> <li>Correlations for friction factor <ul style="list-style-type: none"> <li><math>f = (110 \pm 8) / \text{Re}</math> <math>\text{Re} \leq 900</math></li> <li><math>f = 0.165 (3.48 - \log \text{Re})^{2.4} + (0.081 \pm 0.007)</math> <math>900 &lt; \text{Re} &lt; 3000</math></li> <li><math>f = (0.195 \pm 0.017) / \text{Re}^{0.11}</math> <math>3000 &lt; \text{Re} &lt; 15000</math></li> </ul> </li> </ul>	Wu & Little (1983) [3]
As in [3]	Heat transfer experiments	<ul style="list-style-type: none"> <li>Correlation for Nusselt number in the turbulent regime: <math display="block">\text{Nu} = 0.0022 \text{Pr}^{0.4} \text{Re}^{1.09} \quad \text{Re} &gt; 3000</math> </li> </ul>	Wu & Little (1984) [4]
Rectangular; air in silicon W = 0.13-0.25 mm, H/W = 10, $A_s$ = 47-63 $\text{cm}^2/\text{cm}^3$	Comparison of performance with conventional heat sinks, based on correlations	<ul style="list-style-type: none"> <li>Micro-structured compact heat sinks attractive compared to conventional air circulation heat sinks</li> </ul>	Mahalingam & Andrews (1987) [5]
Rectangular; water in silicon W = 50-600 $\mu\text{m}$	Theoretical model for fully developed, developing flows	<ul style="list-style-type: none"> <li>Turbulent flow designs showed equivalent or better performance compared to laminar flow designs</li> </ul>	Phillips et al. (1989) [6]
Rectangular; N Propanol in silicon $A_c$ = 80-7200 sq. $\mu\text{m}$	Experiments	<ul style="list-style-type: none"> <li>Channels with larger cross-sectional areas showed better agreement with theoretical predictions for the friction factor</li> <li>Proposed <math>f = C/\text{Re}</math> with C given as C vs. Re graphs (laminar)</li> </ul>	Pfahler et al. (1990) [7]
Microchannel structures for cooling applications	Microchannel applications discussed	<ul style="list-style-type: none"> <li>Applications of microchannels to electronics cooling, compact heat exchangers, heat shields and fluid distribution systems discussed</li> </ul>	Hoopman (1990) [8]



Configuration/Parameters	Nature of Work	Observations/Conclusions	Reference
Microtubes; nitrogen in silica D = 3, 7, 10, 53, 81 μm, L = 24-52 mm	Experiments on friction and heat transfer	<ul style="list-style-type: none"> <li>Correlations for friction factor and Nusselt number:  Laminar (<math>Re &lt; 2000</math>) <math>f = 64/Re [1 + 30(v/Dc_a)]^{-1}</math>  Turbulent (<math>2500 &lt; Re &lt; 20000</math>) <math>f = 0.140 Re^{-0.182}</math>  Laminar <math>Nu = 0.000972 Re^{1.17} Pr^{1/3}</math>  Turbulent <math>Nu = 3.82 \times 10^{-6} Re^{1.96} Pr^{1/3}</math> </li> </ul>	Choi et al. (1991) [9]
Rectangular; water in etched silicon W = 1 mm, H = 176-325 μm, L = 46 mm, P = 2 mm	Experiments	<ul style="list-style-type: none"> <li>Nusselt numbers higher than those predicted from analytical solutions for developing laminar flow</li> </ul>	Rahman & Gui (1993) [10]
<b>SINGLE-PHASE (LIQUID) EXPERIMENTS</b>			
Rectangular; deionized water in stainless steel W = 0.6 mm; H = 0.7 mm, $T_i = 30-60^\circ C$ , $v = 0.2-2.1$ m/s	Experiments on single-phase forced convection	<ul style="list-style-type: none"> <li>In single-phase convection, a steep increase in wall heat flux with the wall temperature</li> <li>Heat flux for microchannels higher than for normal-size tube</li> </ul>	Peng & Wang (1993) [11]
Rectangular; water, methanol in stainless steel W = 0.2, 0.4, 0.6, 0.8 mm, H = 0.7 mm, $T_i = 10-35^\circ C$ (water), $14-19^\circ C$ (methanol), $v = 0.2-2.1$ m/s	Experiments on forced convection flow and heat transfer	<ul style="list-style-type: none"> <li>Heat transfer augmented as liquid temperature was reduced and as liquid velocity was increased</li> <li>Fully developed turbulent convection regime starts at <math>Re = 1000-1500</math></li> <li>Correlation for turbulent heat transfer <math>Nu = 0.00805 Re^{4/5} Pr^{1/3}</math></li> </ul>	Wang & Peng (1994) [12]
Rectangular; water in stainless steel $D_h = 0.133-0.367$ mm, L = 50 mm, H/W = 0.333-1, $T_i = 22-44^\circ C$ , $v = 0.25-12$ m/s, $Re = 50-4000$	Experiments on frictional behavior in laminar and turbulent flow	<ul style="list-style-type: none"> <li>Flow transition occurred for <math>Re = 200-700</math></li> <li>Correlations proposed (values for <math>C_{f,l}</math>, <math>C_{f,t}</math> provided in Table 2)  <math>f = C_{f,l}/Re^{1.98}</math> laminar flow  <math>f = C_{f,t}/Re^{1.72}</math> turbulent flow </li> </ul>	Peng et al. (1994a) [13]
As in [13]	Experiments on forced convection heat transfer characteristics	<ul style="list-style-type: none"> <li>Fully turbulent convective conditions reached at <math>Re = 400-1500</math></li> <li>Transition <math>Re</math> diminished with a reduction in microchannel dimension  <math>Nu = C_{h,l} Re^{0.62} Pr^{1/3}</math> Laminar  <math>Nu = C_{h,t} Re^{0.8} Pr^{1/3}</math> Turbulent  (values for <math>C_{h,l}</math>, <math>C_{h,t}</math> provided in Table 2) </li> </ul>	Peng et al. (1994b) [14]
As in [12] except $T_i = 11-28^\circ C$ (water), $12-20^\circ C$ (methanol) $v = 0.2-2.1$ m/s (water), $0.2-1.5$ m/s (methanol)	Experiments on effect of thermofluid properties and geometry on convective heat transfer	<ul style="list-style-type: none"> <li>Changes in flow regimes and heat transfer modes initiated at lower <math>Re</math> in microchannels compared to conventional channels</li> <li>Transition zone and heat transfer characteristics in laminar and transition flow influenced by liquid temperature, velocity, <math>Re</math> and microchannel size</li> </ul>	Peng & Peterson (1995) [15]
As in [13]	Experiments on single-phase flow and heat transfer	<ul style="list-style-type: none"> <li>Ratio of experimental to theoretical friction factor at critical <math>Re</math> plotted as a function of <math>Z (= \min [H, W] / \max [H, W])</math></li> <li>Correlations proposed  <math>Nu = 0.1165 (D_h / P)^{0.81} (H / W)^{-0.79} Re^{0.62} Pr^{0.33}</math> Laminar  <math>Nu = 0.072 (D_h / P)^{1.15} [1 - 2.421 (Z - 0.5)^2] Re^{0.8} Pr^{0.33}</math> Turbulent </li> </ul>	Peng & Peterson (1996a) [16]

Configuration/Parameters	Nature of Work	Observations/Conclusions	Reference
Rectangular; water-methanol mixture in stainless steel $D_h = 0.133\text{--}0.367$ mm, $L = 50$ mm $W = 0.1, 0.2, 0.3, 0.4$ mm, $H = 0.2, 0.3$ mm, $T_i = 14\text{--}36^\circ\text{C}$ , $v = 0.04\text{--}3.8$ m/s, $Re = 6\text{--}3500$	Experiments	<ul style="list-style-type: none"> <li>Laminar heat transfer ceased for <math>Re \approx 70\text{--}400</math> depending on flow conditions; fully developed turbulent heat transfer achieved at <math>Re = 200\text{--}700</math>, depending on <math>D_h</math></li> <li>Transition <math>Re</math> reduced with a reduction in microchannel size</li> <li><math>D_h</math>, <math>H/W</math> and mixture mole fraction influenced heat transfer</li> <li>Heat transfer increased for smaller mole fractions of the more volatile component</li> </ul>	Peng & Peterson (1996b) [17]
Rectangular; deionized water in silicon $W = 251$ $\mu\text{m}$ , $H = 1030$ $\mu\text{m}$ , $D_h = 404$ $\mu\text{m}$ , $L = 2.5$ cm, $Q = 5.47\text{--}118$ cm <sup>3</sup> /s	Experimental & theoretical study	<ul style="list-style-type: none"> <li>Critical <math>Re</math> of 1500 identified for onset of turbulence</li> <li>Analysis showed that flow and heat transfer performance could be improved by increasing <math>H</math>, and that for the same pressure drop and pumping power, thermal resistance was smaller for deeper channels</li> </ul>	Harms et al. (1997) [18]
Rectangular; FC-72 and transformer oil in stainless steel $H = 0.10\text{--}0.58$ mm; nozzle dimensions (mm): Length = 35, $B = 0.146, 0.210, 0.234$ , Height = 12, $v = 0.54\text{--}8.45$ m/s $Re = 70\text{--}170$ (oil), 911–4807 (FC72)	Experiments in impingement on 2D microchannels	<ul style="list-style-type: none"> <li>Empirical correlation for Nusselt number for the two liquids  <math display="block">Nu_x = 0.429 Re^{0.583} Pr^{1/3} (x/2H)^{0.349} (B/2H)^{-0.494}</math> </li> </ul>	Zhuang et al. (1997) [19]
Circular; distilled water in copper $D = 0.102\text{--}1.09$ mm $v < 18.9$ m/s, $Re = 2.6 \times 10^3 - 2.3 \times 10^4$ , $Pr = 1.53\text{--}6.43$ $q'' < 3.0$ MW/m <sup>2</sup>	Experiments on turbulent single-phase flow	<ul style="list-style-type: none"> <li>Nusselt numbers higher than those predicted by large-channel correlations</li> <li>Gnielinski [71] correlation modified for Nusselt number for turbulent flow in circular microchannels (f from Filonenko, 1954):  <math display="block">Nu = Nu_{Gn} (1+F) \text{ where } F = C Re [1-(D/D_o)^2]</math> <math display="block">Nu_{Gn} = (f/8)(Re - 1000)Pr / [1+12.7(f/8)^{1/2}(Pr^{2/3}-1)]</math> <math display="block">C = 7.6 \times 10^{-5}; D_o = 1.164 \text{ mm}, f = [1.82 \log(Re) - 1.64]^{-2}</math> </li> </ul>	Adams et al. (1998) [20]
Non-circular; water in copper $D_h = 1.13$ mm, $Re = 3.9 \times 10^3 - 2.14 \times 10^4$ , $Pr = 1.22\text{--}3.02$	Experiments on turbulent convection	<ul style="list-style-type: none"> <li>Experimental Nusselt number well-predicted by <math>Nu_{Gn}</math></li> <li><math>D_h \approx 1.2</math> mm proposed as reasonable lower limit for applicability of standard Nusselt-type correlations to non-circular channels</li> </ul>	Adams et al. (1999) [21]
Rectangular laminar and transition flow	Dimensional analysis based on experimental data in the literature	<ul style="list-style-type: none"> <li>Attempted to explain the observation that <math>Nu</math> may decrease with increasing <math>Re</math> in laminar regime and may remain unaffected in transition regime</li> <li>Proposed that Brinkman number may better correlate convective heat transfer</li> </ul>	Tso & Mahulikar (1998, 1999) [22, 23]
Almost circular; water in aluminum $D_h = 0.73$ mm	Experiments	<ul style="list-style-type: none"> <li>Laminar flow data found to correlate well using Brinkman number</li> </ul>	Tso & Mahulikar (2000) [24]
<b>SINGLE-PHASE (LIQUID) MODELS AND OPTIMIZATION STUDIES</b>			
Triangular microgrooves channel angle 20–60 deg.	Analytical/numerical analysis	<ul style="list-style-type: none"> <li>Friction factor-Reynolds number product strongly dependent on channel angle, contact angle, and dimensionless vapor-liquid interface flow number</li> </ul>	Ma et al. (1994) [25]

Configuration/Parameters	Nature of Work	Observations/Conclusions	Reference
Microchannel plate-fin heat sink; air in copper, aluminum $W = 400, 500 \mu\text{m}$ , $H = 2.5 \text{ cm}$ , $Q = 1\text{-}6 \text{ l/s}$	Thermal resistance model, experiments, optimization	<ul style="list-style-type: none"> <li>Thermal resistance of microchanneled heat sink lower than for heat sinks employing direct air cooling, by a factor of more than 3</li> </ul>	Kleiner et al. (1995) [26]
Circular capillary channels $D = 8.1\text{-}96 \mu\text{m}$ , $0.76\text{-}4.7 \mu\text{m}$	Numerical study on the flow of superfluid Helium using a "two-fluid model"	<ul style="list-style-type: none"> <li>Existence of an optimum channel diameter for maximum mass flow rate indicated</li> </ul>	Takamatsu et al. (1997) [27]
Rectangular; fluorocarbon in silicon $P = 100\text{-}1000 \mu\text{m}$ , $H = 150\text{-}200 \mu\text{m}$ , $W = 56.6\text{-}113.4 \mu\text{m}$ , $v = 0.1\text{-}1.0 \text{ m/s}$	Numerical analysis of manifold microchannel heat sinks	<ul style="list-style-type: none"> <li>3D model showed close agreement with simple 1D model at high inlet velocity</li> <li>Numerical results showed much weaker effect of <math>W</math> compared to analytical results</li> <li><math>L</math> had almost no effect on thermal resistance and affected only pressure drop</li> </ul>	Copeland et al. (1997) [28]
Parallel plates at $25 \mu\text{m}$ separation dilute aqueous electrolyte $L = 10 \text{ mm}$	Theoretical analysis incorporating effects of electric double layer field	<ul style="list-style-type: none"> <li>EDL resulted in a reduced flow velocity than in conventional theory, thus affecting temperature distribution and reducing <math>Re</math></li> <li>Higher heat transfer predicted without the double layer</li> </ul>	Mala et al. (1997a) [29]
Parallel plates ( $10 \times 20 \text{ mm}$ ) of P-type silicon and glass at $10\text{-}280 \mu\text{m}$ separation; $\Delta P = 0\text{-}350 \text{ mbar}$	Experimental study and comparison with predicted volume flow rates	<ul style="list-style-type: none"> <li>For solutions of high ionic concentration as well as for <math>D_h &gt; \text{few hundred } \mu\text{m}</math>, EDL effect negligible</li> <li>EDL effect becomes significant for dilute solutions</li> </ul>	Mala et al. (1997b) [30]
Rectangular; dilute aqueous electrolyte in silicon $H = 20 \mu\text{m}$ , $W = 30 \mu\text{m}$ , $L = 10 \text{ mm}$ , $\Delta P = 2 \text{ atm}$ , $T_i = 298 \text{ K}$ , $q'' = 1.0 \times 10^5 \text{ W/m}^2$	Numerical analysis with effects of EDL and flow-induced electrokinetic field	<ul style="list-style-type: none"> <li>The EDL field and electrokinetic potential act against the liquid flow, resulting in higher friction coefficient, reduced flow rate and a reduced Nusselt number, for dilute solutions</li> </ul>	Yang et al. (1998) [31]
Rectangular (flat plate micro heat exchangers)	Optimization study on microchannel shape	<ul style="list-style-type: none"> <li>Width of heat exchanger conduits may be optimized to reduce maximum temperature of the uniformly heated surface</li> </ul>	Bau (1998) [32]
Microchannel cooling and jet impingement	Comparative analysis of jet impingement and microchannel cooling	<ul style="list-style-type: none"> <li>Thermal performance of jet impingement without any treatment of spent flow substantially lower than microchannel cooling, regardless of target dimension</li> <li>Microchannel cooling preferable for target dimensions smaller than <math>7 \times 7 \text{ cm}</math></li> </ul>	Lee and Vafai (1999) [33]
<b>GAS FLOW</b>			
Rectangular; helium in silicon $W = 52.25 \mu\text{m}$ , $H = 1.33 \mu\text{m}$ , $L = 7500 \mu\text{m}$ ; Inlet to outlet pressure ratio = $1.2\text{-}2.5$ , $Re = (0.5\text{-}4) \times 10^{-3}$	Flow rates measured and compared with theoretical model	<ul style="list-style-type: none"> <li>Mass flow–pressure relationship accurately modeled by including a slip flow boundary condition at the wall</li> </ul>	Arkilic et al. (1994) [34]
As in [34] with pressure ratio = $1.6\text{-}4.2$ , $Re = (1.4\text{-}12) \times 10^{-3}$	Experiments and comparison of mass flow with results from 2D analysis with slip boundary condition	<ul style="list-style-type: none"> <li>Discussions on nondimensional formulation and perturbation solution</li> </ul>	Arkilic et al. (1997) [35]

Configuration/Parameters	Nature of Work	Observations/Conclusions	Reference
Microtubes; nitrogen and water in silica D = 19, 52, 102 $\mu\text{m}$ , Pr = 0.7-5, Re = 250-20000	Experiments; theoretical scaling analysis	<ul style="list-style-type: none"> <li>Turbulent momentum and energy transport in the radial direction significant in the near-wall zone of a microtube</li> <li>Correlations proposed:  <math>f = 50.13/\text{Re}</math> (laminar, Re &lt; 2000)  <math>f = 0.302/\text{Re}^{0.25}</math> (transition, 2000 &lt; Re &lt; 6000)  <math>\text{Nu} = 0.007\text{Re}^{1.2} \text{Pr}^{0.2}</math> (turbulent, 6000 &lt; Re &lt; 20000) </li> </ul>	Yu et al. (1995) [36]
Rectangular H = 0.5, 5 $\mu\text{m}$ , H/W = 2.5, 5, 10, 20 (subsonic); 5, 10, 20 (supersonic)	Numerical study using direct simulation Monte Carlo technique	<ul style="list-style-type: none"> <li>Heat flux on the channel surface decreases with increase in Knudsen number and channel length in supersonic flow</li> </ul>	Mavriplis et al. (1995) [37]
Rectangular helium (as in [34]) helium and nitrogen, $D_h = 1.01\mu\text{m}$ , L = 10.9 mm (as in [38])	2D numerical model, comparison with experiments in literature	<ul style="list-style-type: none"> <li>Nusselt number and friction coefficient substantially reduced for slip flows compared to continuum flows</li> <li>Effect of compressibility significant at high Re</li> </ul>	Kavehpour & Faghri (1997) [39]
Smooth microtubes Gas flow	Numerical solution of gas flow in microtubes	<ul style="list-style-type: none"> <li>Local Nusselt number increased with dimensionless length, due to compressibility</li> <li>f-Re product not constant; dependent on Re</li> </ul>	Guo & Wu (1997) [40]
Rectangular; nitrogen, helium in silicon W = 40 $\mu\text{m}$ , H = 1.2 $\mu\text{m}$ , L = 3 mm ( $\text{N}_2$ ), W = 52 $\mu\text{m}$ , H = 1.33 $\mu\text{m}$ , L = 7.5 mm (He)	Numerical solution with slip boundary condition	<ul style="list-style-type: none"> <li>Small velocities and high pressure gradients due to large wall shear stresses</li> <li>Comparisons with experiments of [34]</li> </ul>	Chen et al. (1998) [41]
3D straight and spiral grooves	Numerical study on slip flow in long microchannels	<ul style="list-style-type: none"> <li>Non-linear pressure gradients along the microchannels due to density variations</li> </ul>	Niu (1999) [42]
<b>BOILING IN MICROCHANNELS</b>			
Circular; R-113 in copper D = 2.45 mm (mini), 510 $\mu\text{m}$ (micro) Q = 19-95 ml/min, $\Delta T$ : 10-32°C	Experiments on boiling & two- $\phi$ flow; boiling curves & CHF values obtained	<ul style="list-style-type: none"> <li>Microchannel yielded higher CHF (28% greater at Q = 64 ml/min) than mini channel, with a larger <math>\Delta P</math> (0.3 bar for micro, 0.03 bar for mini)</li> </ul>	Bowers & Mudawar (1994a) [43]
As in [43]	Pressure drop model developed; predictions compared to experiments	<ul style="list-style-type: none"> <li>Major contributor to pressure drop identified as the acceleration resulting from evaporation</li> <li>Compressibility effect important for microchannel when Mach number &gt; 0.22</li> <li>Channel erosion effects more predominant in microchannels than in mini channels</li> </ul>	Bowers & Mudawar (1994b) [44]
As in [43]	Experiments on boiling and two-phase flow	<ul style="list-style-type: none"> <li>Single CHF correlation for mini and microchannels developed:  <math>q_{m,p} / (G h_{fg}) = 0.16 We^{-0.19} (L/D)^{0.54}</math> </li> </ul>	Bowers & Mudawar (1994c) [45]

Configuration/Parameters	Nature of Work	Observations/Conclusions	Reference
Rectangular; water in stainless steel $W = 0.6$ mm, $H = 0.7$ mm, $T_i = 30$ - $60^\circ\text{C}$ , $v = 1.5$ - $4.0$ m/s	Experiments on subcooled boiling of water	<ul style="list-style-type: none"> <li>Nucleate boiling intensified and wall superheat for flow boiling smaller in microchannels than in normal-sized channels for the same wall heat flux</li> <li>No partial nucleate boiling observed in microchannels</li> </ul>	Peng & Wang (1993) [11]
Rectangular; methanol in stainless steel $W = 0.2, 0.4, 0.6$ mm, $H = 0.7$ mm, $L = 45$ mm, $P = 2.4$ - $4$ mm; $T_i = 14$ - $19^\circ\text{C}$ (Subcooling: $45$ - $50^\circ\text{C}$ ), $v = 0.2$ - $1.5$ m/s	Experiments on boiling	<ul style="list-style-type: none"> <li>Liquid velocity and subcooling do not affect fully developed nucleate boiling</li> <li>Greater subcooling increased velocity and suppressed initiation of flow boiling</li> </ul>	Peng et al. (1995) [46]
Rectangular; methanol-water mixture in stainless steel $W = 0.1, 0.2, 0.3, 0.4$ mm, $H = 0.2, 0.3$ mm, $L = 45$ mm, $D_h = 0.133$ - $0.343$ mm, $v = 0.1$ - $4.0$ m/s, $T_i = 18$ - $27.5^\circ\text{C}$ (Subcooling: $38$ - $82^\circ\text{C}$ )	Experiments on flow boiling in binary mixtures	<ul style="list-style-type: none"> <li>Heat transfer coefficient at onset of flow boiling and in partial nucleate boiling greatly influenced by concentration, microchannel/substrate dimensions, flow velocity and subcooling</li> <li>These parameters had no significant effect on heat transfer coefficient in the fully nucleate boiling regime</li> <li>Mixtures with small concentrations of methanol augmented flow boiling heat transfer</li> </ul>	Peng et al. (1996) [47]
V-shaped; water and methanol in stainless steel Groove angle: $30$ - $60$ deg; $D_h = 0.2$ - $0.6$ mm $v$ (water) = $0.31$ - $1.03$ m/s $v$ (methanol) = $0.12$ - $2.14$ m/s	Experiments on flow boiling	<ul style="list-style-type: none"> <li>Heat transfer and pressure drop were affected by flow velocity, subcooling, <math>D_h</math> and groove angle</li> <li>No bubbles observed in microchannels during flow boiling, unlike in conventional channels</li> <li>Experiments indicated an optimum <math>D_h</math> and groove angle</li> </ul>	Peng et al. (1998) [48]
V-shaped	Analysis of microgrooves with non-uniform heat input	<ul style="list-style-type: none"> <li>Analytical expression developed for the evaporating film profile</li> </ul>	Ha & Peterson (1996) [49]
V-shaped	Analysis of axial flow of evaporating thin film	<ul style="list-style-type: none"> <li>Used perturbation method to solve the axial flow of an evaporating thin film through a V-shaped microchannel with tilt</li> </ul>	Ha & Peterson (1998) [50]
Circular and rod bundle; water in copper $D = 1.17, 1.45$ mm, $D_h = 1.131$ mm $m = 250$ - $1000$ kg/m <sup>2</sup> s Exit pressure = $344$ - $1043$ kPa Inlet pressure = $407$ - $1204$ kPa $T_i = 49$ - $72.5^\circ\text{C}$	Experiments on CHF in flow of subcooled water	<ul style="list-style-type: none"> <li>CHF found to increase monotonically with increasing mass flux or pressure</li> <li>CHF depends on the channel cross section geometry, and increases with increasing <math>D</math></li> </ul>	Roach et al. (1999) [51]
<b>BOILING IN SMALL DIAMETER TUBES AND CHANNELS</b>			
Circular; water in stainless steel $D = 2.5$ mm, $t = 0.25$ mm, $v = 10$ - $40$ m/s	Experiments on subcooled flow boiling of water under high heat fluxes	<ul style="list-style-type: none"> <li>Experimental data did not match predictions from CHF correlations in the literature</li> </ul>	Celata et al. (1993) [52]
Rectangular; water and R141b in copper $W = 1, 2, 3$ mm, $H/W < 3$ , $m = 50, 200, 300$ kg/m <sup>2</sup> s	Experiments on flow boiling in narrow channels of planar heat exchanger elements	<ul style="list-style-type: none"> <li>Boiling curves and variations of heat transfer coefficient with local and average heat fluxes obtained</li> </ul>	Mertz et al. (1996) [53]

Configuration/Parameters	Nature of Work	Observations/Conclusions	Reference
Rectangular; FC-72 in fiberglass W = 5 mm, H = 2.5 mm, Heated length = 101.6 mm, v = 0.25-10 m/s, Re = 2000-130000 Subcooling at outlet = 3, 16, 29°C	CHF experiments on long channels; flow visualization	<ul style="list-style-type: none"> <li>Propagation of vapor patches resembling a wavy vapor layer along the heated wall at the critical heat flux</li> <li>Length and height of vapor patch found to increase along flow direction, and decreased with increasing subcooling and velocity</li> </ul>	Sturgis & Mudawar (1999a) [54]
As in [54]	Theoretical model for CHF; data analysis	<ul style="list-style-type: none"> <li>Effect of periodic distribution of vapor patches idealized as a sinusoidal interface with amplitude and wavelength increasing in flow direction</li> </ul>	Sturgis & Mudawar (1999b) [55]
<b>TWO-PHASE FLOW</b>			
Rectangular; R124 in copper W = 0.27 mm, H = 1.0 mm, D <sub>h</sub> = 425 μm, Re <sub>Dh</sub> = 100-750; q'' < 40 W/cm <sup>2</sup>	Experiments on microchannel heat exchanger	<ul style="list-style-type: none"> <li>Nusselt number (~ 5 to 12) showed an increase with Reynolds number in single-φ flow, but was approximately constant in two-φ flow</li> </ul>	Cuta et al. (1996) [56]
Rectangular; R124 in copper W = 270 μm, H = 1000 μm, L = 2.052 cm, D <sub>h</sub> = 425 μm; Inlet subcooling: 5-15°C; Q = 35-300 ml/min	Experiments with two microchannel patterns (parallel and diamond)	<ul style="list-style-type: none"> <li>Heat transfer coefficient and pressure drop found to be functions of flow quality and mass flux, in addition to the heat flux and surface superheat</li> <li>Heat transfer coefficient decreased by 20-30% for an increase in exit vapor quality from 0.01 to 0.65</li> </ul>	Ravigururajan (1998) [57]
Circular and semi-triangular; air-water mixture in glass D = 1.1, 1.45 mm, D <sub>h</sub> = 1.09, 1.49 mm, v(air): 0.02-80 m/s, v(water): 0.02-8 m/s (superficial velocity)	Visual observation of flow patterns and pattern maps	<ul style="list-style-type: none"> <li>Bubbly, churn, slug, slug-annular and annular flow patterns observed</li> </ul>	Triplett et al. (1999a) [58]
As in [58]	Frictional pressure drops measured and compared with various two-φ friction models	<ul style="list-style-type: none"> <li>Models and correlations overpredicted channel void fraction and pressure drop in annular flow pattern</li> <li>Annular flow interface momentum transfer and wall friction in microchannels significantly different from those in larger channels</li> </ul>	Triplett et al (1999b) [59]
Circular and rectangular; air-water mixture in glass D <sub>h</sub> = 1.3-5.5 mm; v = 0.1-100 m/s (gas); v = 0.01-10 m/s (liquid)	Experiments, flow visualization	<ul style="list-style-type: none"> <li>Tube diameter influences the superficial gas and liquid velocities at which flow transitions take place, due to combined effect of surface tension, hydraulic diameter and aspect ratio</li> </ul>	Coleman & Garimella (1999) [60]
<b>DESIGN AND TESTING</b>			
Rectangular; water in silicon	Numerical solution for temperature field; comparison with experiments [61]	<ul style="list-style-type: none"> <li>Design algorithm developed for selection of heat exchanger dimensions</li> <li>Expression for maximum pumping power obtained as function of channel geometry</li> </ul>	Weisberg et al. (1992) [62]

Configuration/Parameters	Nature of Work	Observations/Conclusions	Reference
Almost rectangular; water in copper 0.5 x 12 mm, 0.125 x 12 mm Q = 0.47-5 gpm	Design and testing, microchannel heat exchanger for laser diode arrays	<ul style="list-style-type: none"> <li>Thermal resistance due to solder bond estimated</li> </ul>	Roy & Avanic (1996) [63]
Rectangular and almost triangular; air in copper, aluminum	Parametric studies and experiments of air impingement in microchannels	<ul style="list-style-type: none"> <li>Thermal resistance model developed</li> <li>Parametric studies to determine influence of static pressure, pumping power and geometric parameters on thermal resistance</li> </ul>	Aranyosi et al (1997) [64]
Rectangular, diamond-shaped and hexagonal; water in silicon	3D numerical model; optimization for reducing thermal resistance	<ul style="list-style-type: none"> <li>Rectangular geometry had the lowest thermal resistance</li> </ul>	Perret et al. (1998) [65]
Rectangular; water, FC72 in copper	Experiments on micro heat sink for power multichip module; 3D and 1D thermal resistance models	<ul style="list-style-type: none"> <li>Power densities of 230-350 W/cm<sup>2</sup> dissipated with a temperature rise of 35°C, and a pumping power of about 1W per chip</li> <li>Parameter 'heat spread effect' defined <math display="block">S = (R_{th1D} - R_{th3D}) / R_{th1D}</math></li> </ul>	Gillot et al. (1998) [66]
Rectangular; water, FC72 in copper W = 230, 311 μm, H = 730, 3040 μm, Q (ml/min) = 1350 (water, 1-φ) and 30 (2- φ); 2000 (FC 72 1-φ) and 300 (2-φ)	Experiments on single and two-phase micro heat exchangers for cooling transistors	<ul style="list-style-type: none"> <li>Two-phase heat exchanger provided lower thermal resistance and pressure drop compared to single-phase heat exchangers</li> </ul>	Gillot et al. (1999) [67]
Rectangular; air in copper W = 800 μm, H = 50 mm, Q = 140 m <sup>3</sup> /hr	Experiments and thermal resistance model	<ul style="list-style-type: none"> <li>Pressure drop found to have large deviation from predicted values at high air flow rates</li> <li>Cooling capacity ≈ 1700 W at heat flux ≈ 15 W/cm<sup>2</sup></li> </ul>	Yu et al. (1999) [68]
<b>MEASUREMENT TECHNIQUES</b>			
Triangular; water in silicon W = 28-182 μm, Q = 0.01-1000 μl/min	Optical flow measurements using microscope	<ul style="list-style-type: none"> <li>Measured flow rates in good agreement with theoretical values for laminar flow through triangular channels</li> </ul>	Richter et al. (1997) [69]
Rectangular; water in glass W = 300 , H = 30, L = 25 mm	Particle image velocimetry	<ul style="list-style-type: none"> <li>Results agreed well with analytical solutions for Newtonian flow in rectangular channels</li> </ul>	Meinhart et al. (1999) [70]

## NOMENCLATURE

$A_c$	cross sectional area	$k_c$	coolant thermal conductivity	$R_{th\ 3D}$	thermal resistance from 3D analysis
$A_s$	surface area	$L$	length	$Re$	Reynolds number
$B$	slot width	$Nu$	Nusselt number	$T_i$	inlet temperature
$C$	coolant heat capacity	$Nu_{Gn}$	Nusselt number (Gnielinski correlation)	$t$	tube wall thickness
$C_a$	acoustic velocity	$P$	channel pitch	$v$	inlet velocity
$D$	diameter	$Pr$	Prandtl number	$W$	width of microchannel
$D_h$	hydraulic diameter	$\Delta P$	pressure drop	$We$	Weber number
$f$	friction factor	$Q$	volumetric flow rate	$x$	distance from stagnation point
$G$	mass velocity ( $\equiv m$ , mass flux)	$q_{m,p}$	CHF based on heated channel area	$\rho$	density
$H$	height (depth) of microchannel	$R_{th\ 1D}$	thermal resistance from 1D analysis	$\mu$	dynamic viscosity
$h_{fg}$	latent heat of vaporization			$\nu$	kinematic viscosity



**Table 2. Microchannel configurations and coefficients from Peng et al. [13, 14].**

Case	W, mm	H, mm	L, mm	D <sub>h</sub> , mm	H/W	Re <sub>cr</sub>	C <sub>f,l</sub>	C <sub>f,t</sub>	C <sub>h,l</sub>	C <sub>h,t</sub>
A	0.4	0.3	50	0.343	0.75	700	44800	34200	0.058	0.0134
B	0.3	0.3	50	0.3	0.1	700	109000	38600	0.0384	0.00726
C	0.4	0.2	50	0.267	0.5	700	28600	40400	0.0426	0.0166
D	0.3	0.2	50	0.24	0.667	400	42600	18200	0.0472	*
E	0.2	0.2	50	0.2	1	200	32400	20100	0.0468	0.00696
F	0.3	0.1	50	0.15	0.333	200	24200	6920	0.0104	0.00483
G	0.2	0.1	50	0.133	0.5	200	5200	1820	0.0285	0.00939